



## Material Content Data Sheet



<b>Sales Product Name</b>		IPP65R310CFDA		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000919056							
<b>Package</b>		PG-TO220-3-1		<b>Weight*</b>		2036.67 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	6.035	0.30	0.30	2963	2963	
leadframe	non noble metal	iron	7439-89-6	1.407	0.07		691		
	inorganic material	phosphorus	7723-14-0	0.422	0.02		207		
	non noble metal	copper	7440-50-8	1404.801	68.98	69.07	689754	690652	
wire	non noble metal	aluminium	7429-90-5	2.883	0.14	0.14	1416	1416	
encapsulation	organic material	carbon black	1333-86-4	8.923	0.44		4381		
	plastics	epoxy resin	-	98.152	4.82		48193		
	inorganic material	silicondioxide	60676-86-0	487.787	23.95	29.21	239502	292076	
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10538	10538	
plating	non noble metal	nickel	7440-02-0	0.244	0.01		120		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	120	
solder	noble metal	silver	7440-22-4	0.114	0.01		56		
	non noble metal	tin	7440-31-5	0.091	0.00		45		
	non noble metal	lead	7439-92-1	4.346	0.21	0.22	2134	2235	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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